ABSTRACT

A manufacturing method of a substrate for a semiconductor element includes a first step and a second step, wherein the first step includes the steps of: forming a first photosensitive resin layer on a first surface of a metal plate; providing a second photosensitive resin layer on a second surface; forming a first resist pattern on the first surface for forming a connection post; and forming a second resist pattern on the second surface of the metal plate for forming a wiring pattern; and wherein the second step includes the steps of: forming the connection post on the first surface; filling in a premold liquid resin to the first surface which was etched; forming a premold resin layer by hardening the premold liquid resin; performing a grinding operation on the first surface, and exposing an upper bottom surface of the connection post from the premold resin layer; and forming the wiring pattern on the second surface; wherein a groove structure is formed at a peripheral of a pattern of a main body of the substrate by going through the first step and the second step, wherein a depth of the groove structure is up to an intermediate part in a thickness direction of the metal plate.

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